

# A Highly Reliable and Tamper-Resistant RRAM PUF: Design and Experimental Validation

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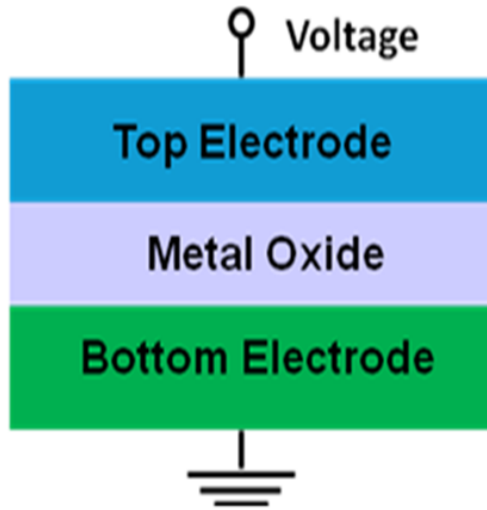
# Outline

- **Introduction of RRAM**
- **RRAM PUF Architecture for Key Generation**
- **Performance Evaluation on 1kb RRAM arrays**
- **Strategies to Improve Performance and Reliability**
- **Area Cost and Performance Overhead Analysis**
- **Conclusion**

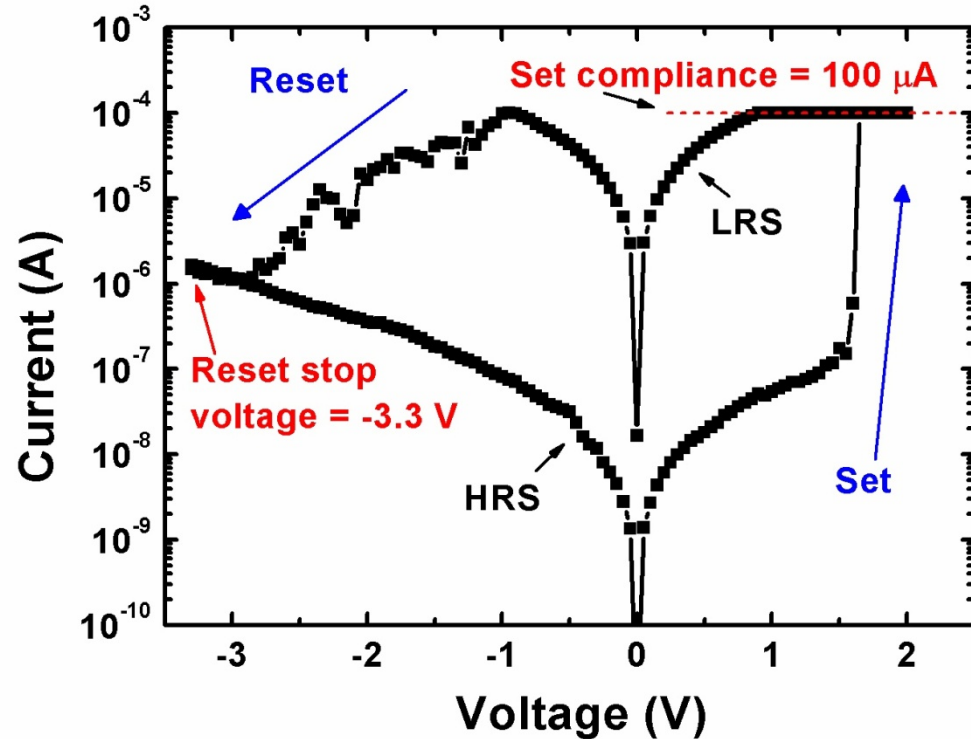
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# Oxide RRAM Basics

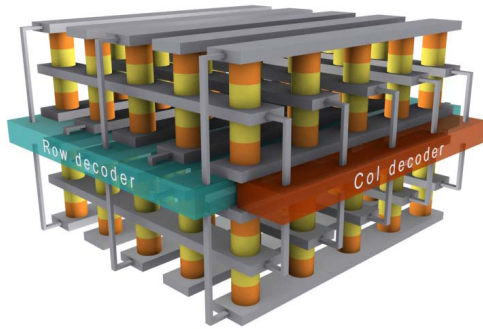


## Typical Bipolar I-V Curve

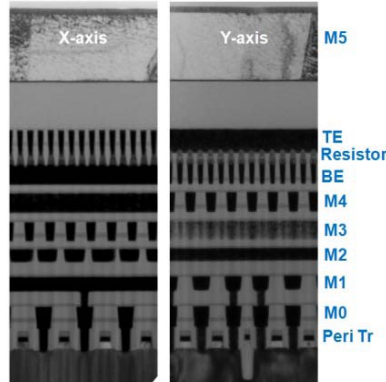


- “0” : High Resistance State (HRS)
- “1” : Low Resistance State (LRS)
- HRS  $\rightarrow$  LRS: SET
- LRS  $\rightarrow$  HRS: RESET

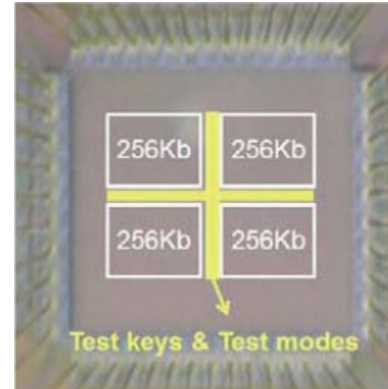
# RRAM's Industry R&D



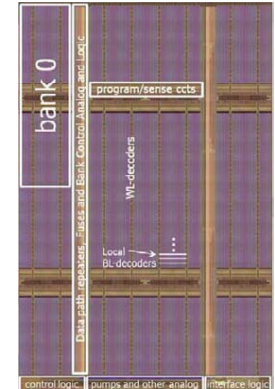
Samsung



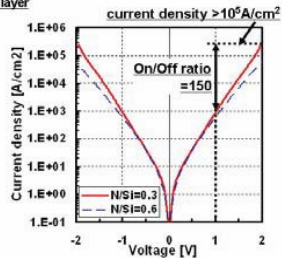
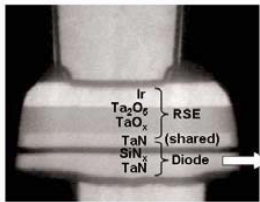
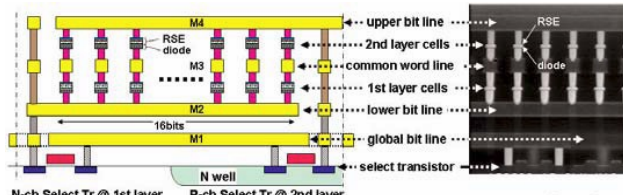
HP & Hynix



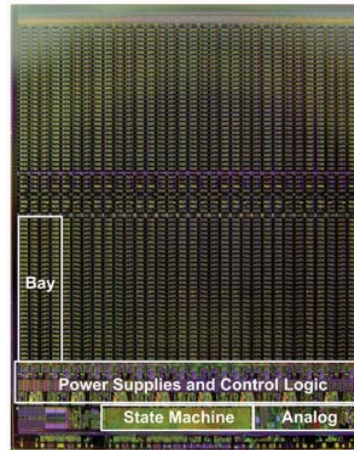
TSMC



Micron & Sony

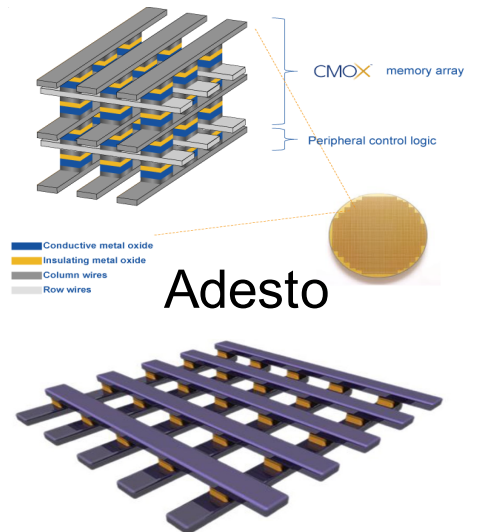


Panasonic



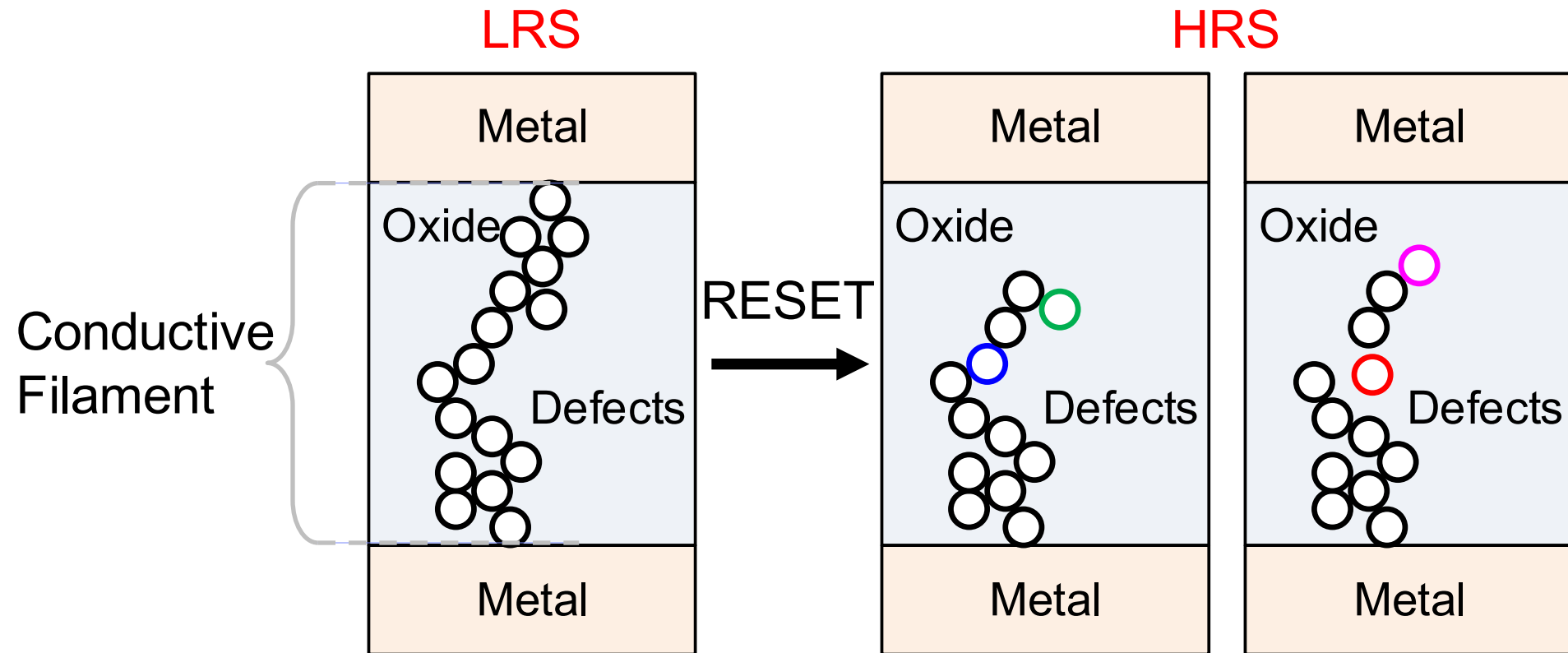
Toshiba & Sandisk

Density	32Gb
Cell Size	24nm x 24nm
Die Size	130.7mm <sup>2</sup>
Interface	NAND- Compatible
Page Size	2KB
Read Latency	40us
Write Latency	230us



# The Randomness in RRAM PUF

- **A small change in defect location significantly changes the resistance due to electron tunneling mechanism in HRS**



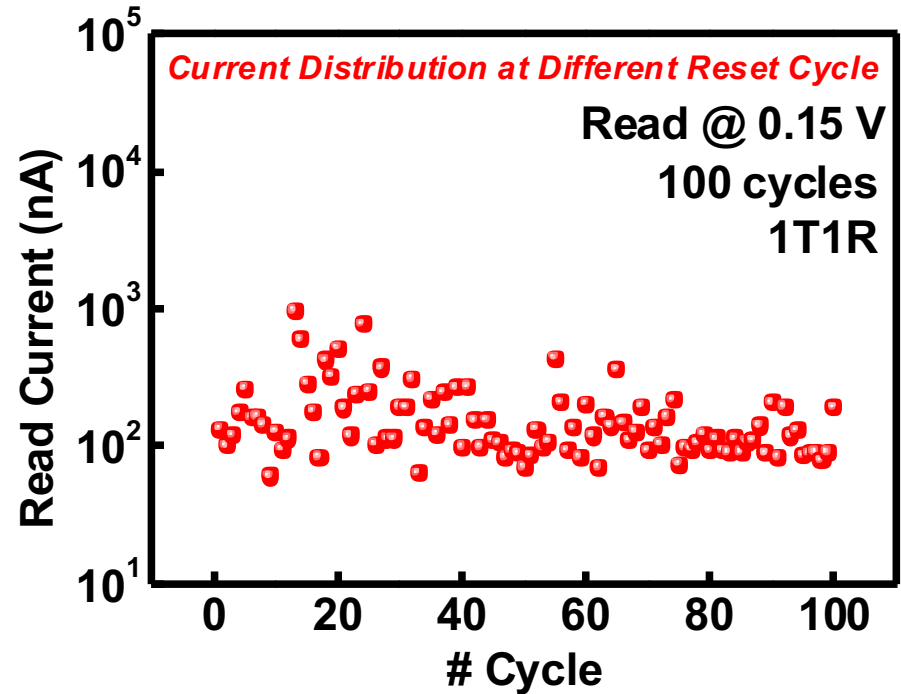
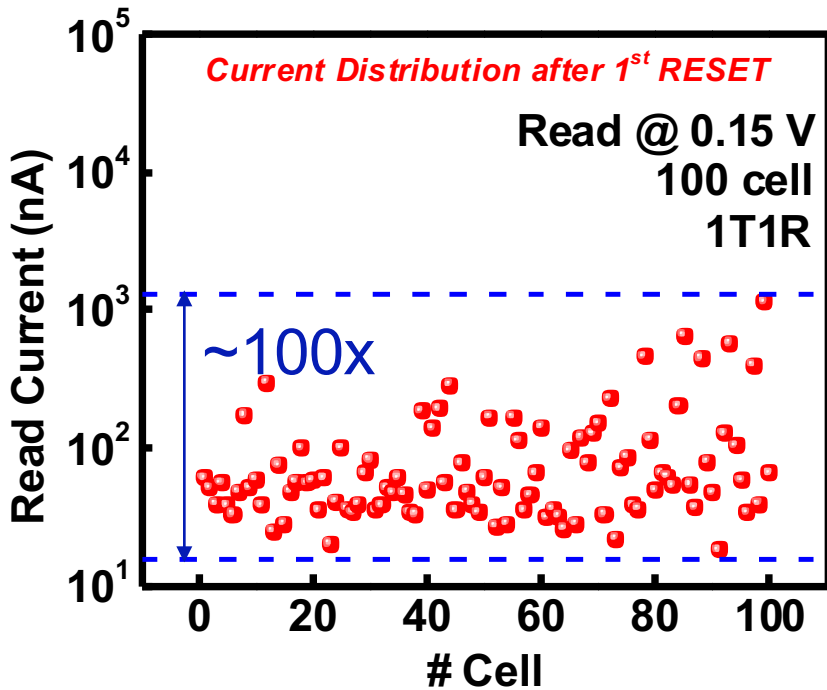
# RRAM Device Characteristics from Experimental Data

**RRAM device: TiN/TaOx/HfO<sub>2</sub>/TiN**

**Cell to Cell**

**Cycle to Cycle**

RESET Pulse: 3V, 50ns



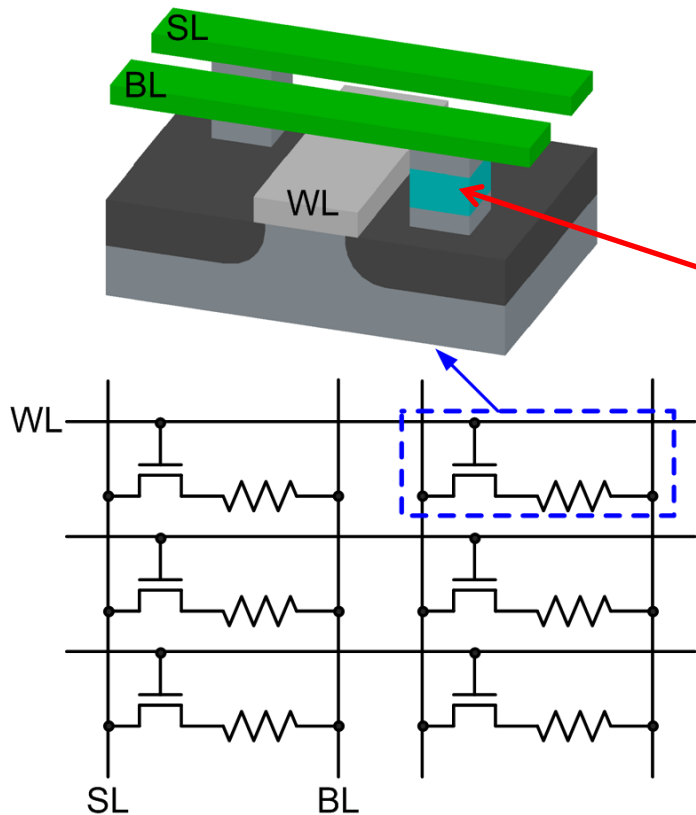
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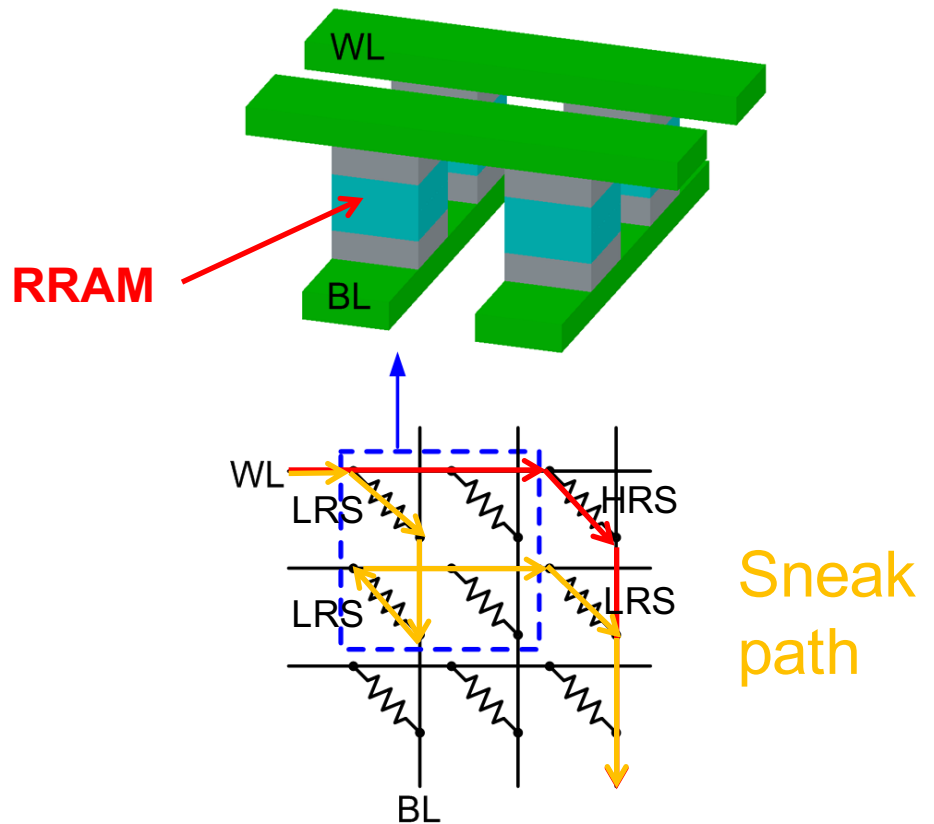


# RRAM Array: 1-transistor-1-resistor (1T1R) vs. Crossbar Architecture

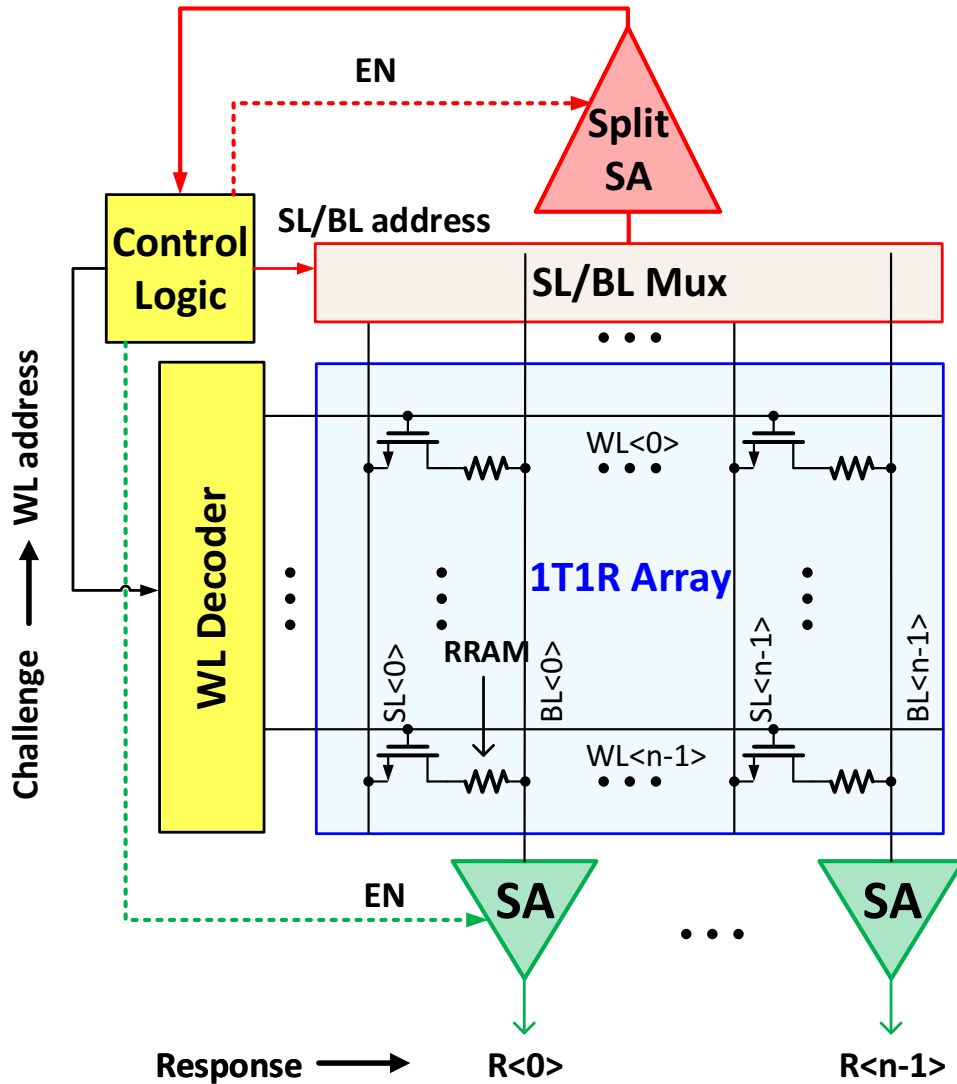
## 1T1R architecture



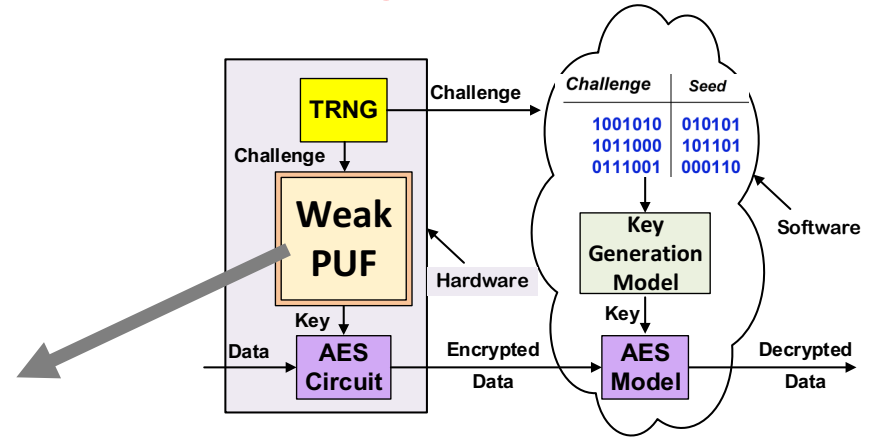
## Crossbar architecture



# RRAM PUF Architecture for Key Generation

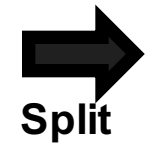
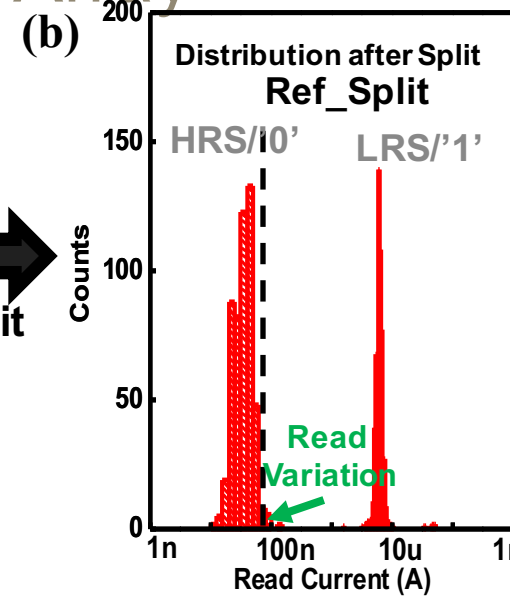
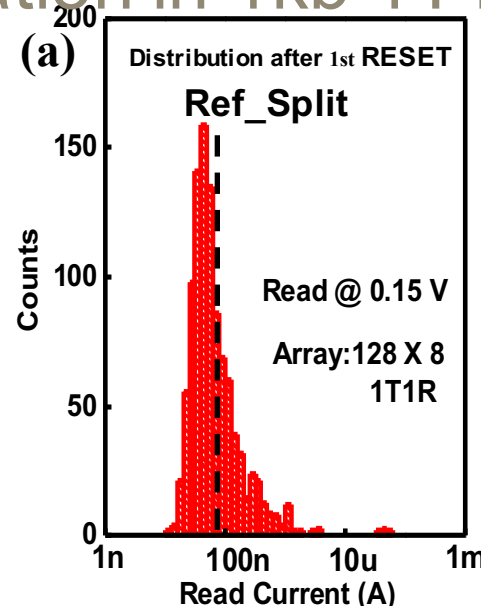
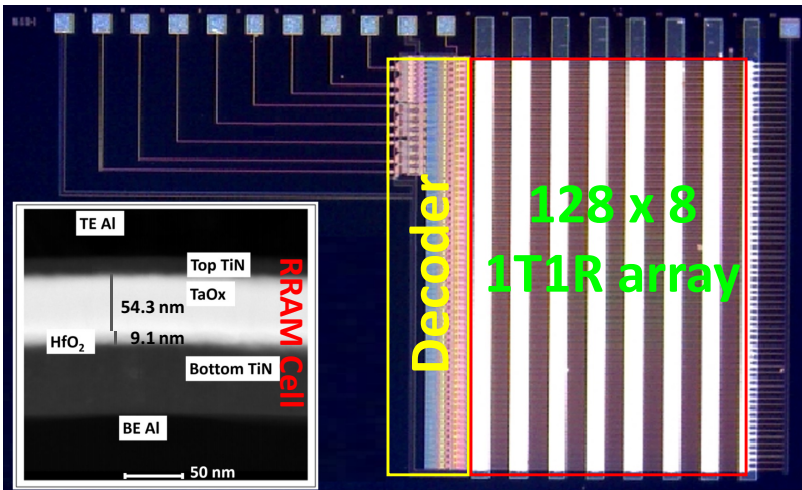


## Key Generation

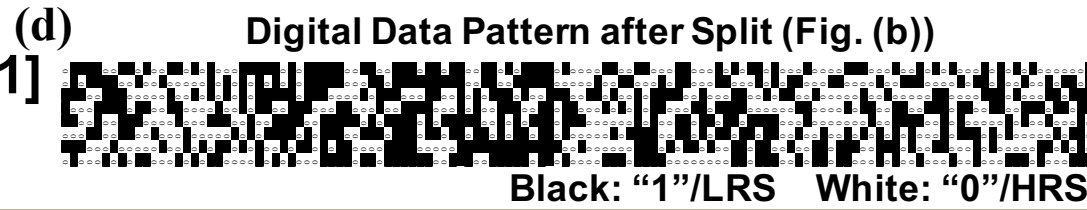
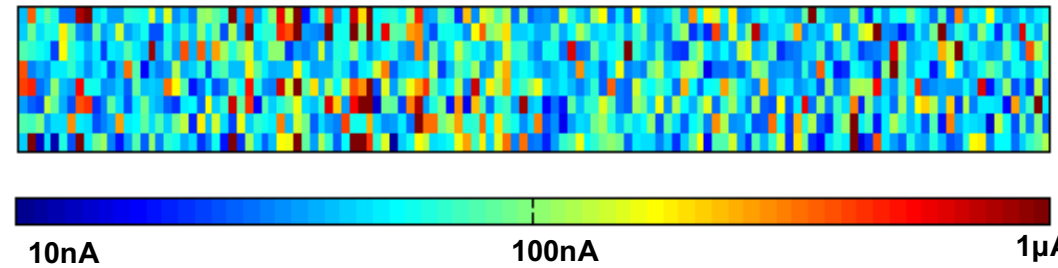


- The red parts are designed only for construction phase (preparation phase)
- The green part is designed only for operation phase (evaluation phase)

# RRAM PUF Implementation in 1kb 1T1R Array



(c) Analog Current Distribution after First RESET Operation (Fig. (a))



- 1) form all the cells to LRS
- 2) RESET all the cells to HRS (entropy source)
- 3) Read out the current
- 4) Find a split reference within the read current distribution
- 5) Digitize the randomness according to the reference [1]

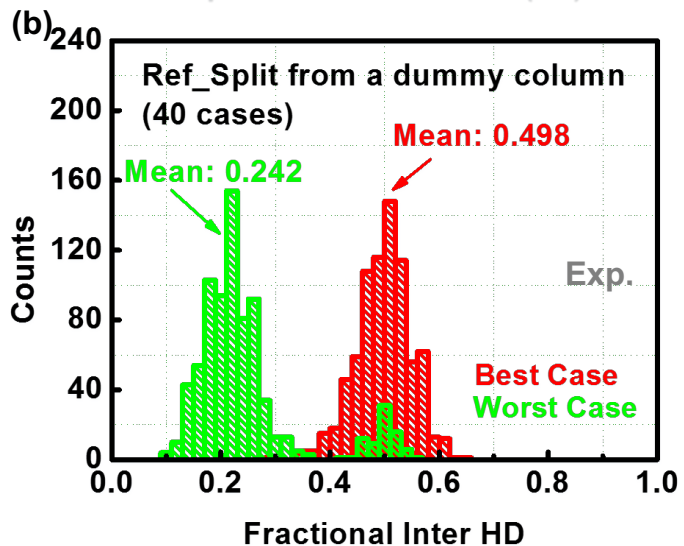
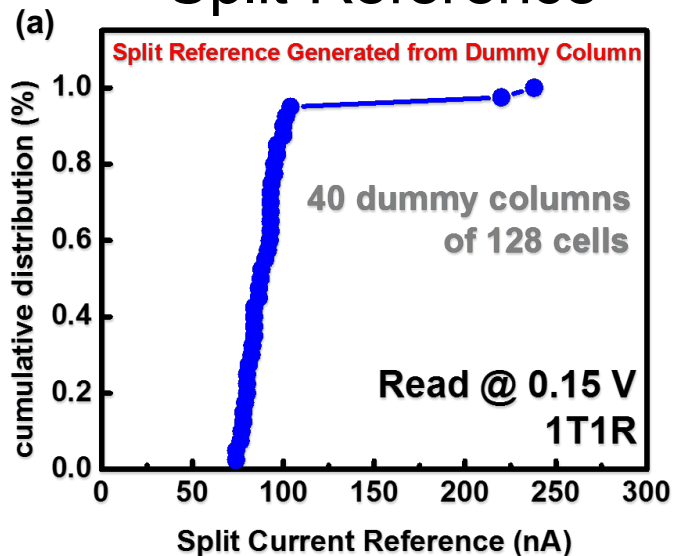
[1] W. Chen, et al, ICCAD, 2014

# Outline

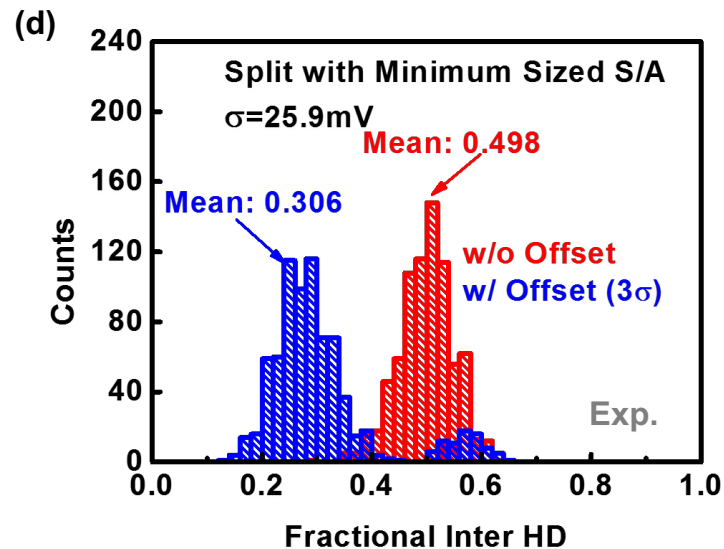
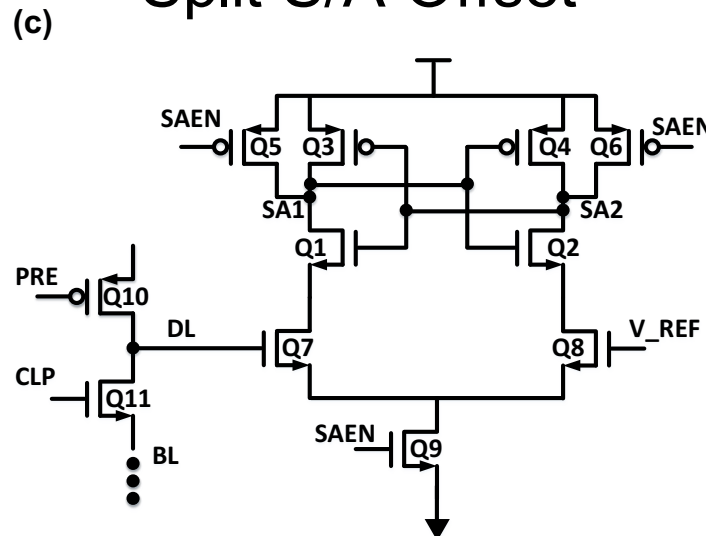
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# Impacts on Uniqueness

## Split Reference

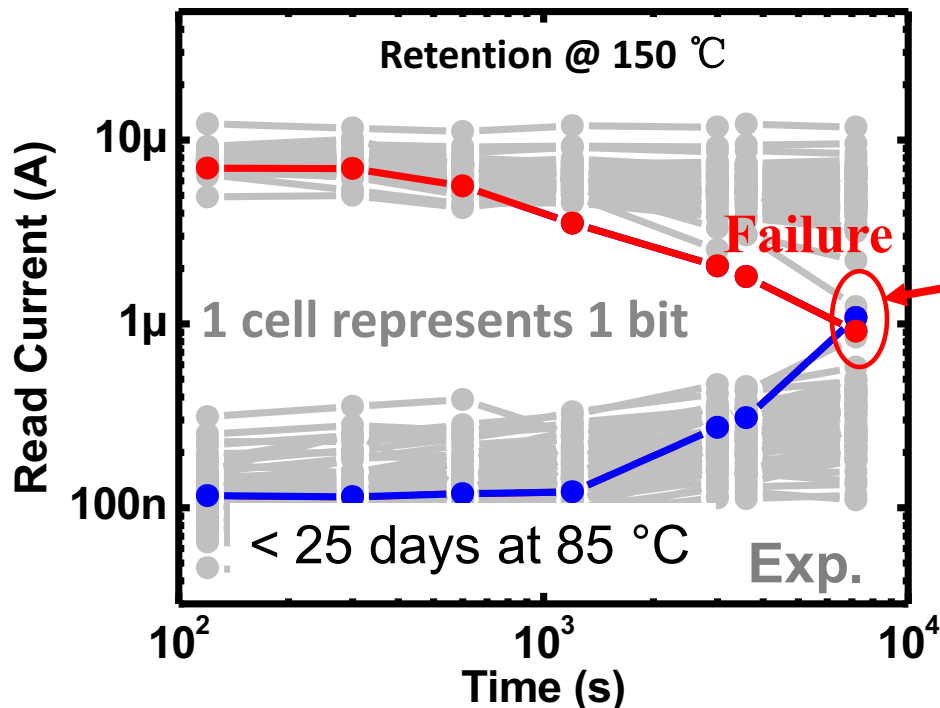


## Split S/A Offset



# Reliability

- **RRAM device: resistance drifts over time but very slow**
- **High temperature is used to accelerate the failure**
- **Reliability of RRAM PUF requires an excellent data retention even at elevated temperature conditions**



Some response bits flipped. The generated key is not reliable.

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## Strategies to Improve Uniqueness

- **Dummy array (1024 cells) is used to generate split reference**

Uniqueness	Ref_Split generated from Array No.				
	1 <sup>st</sup>	2 <sup>nd</sup>	3 <sup>rd</sup>	4 <sup>th</sup>	5 <sup>th</sup>
$\mu(\%)^a$	49.48	48.97	49.79	<b>47.77</b>	49.80
$\sigma(\%)^b$	4.90	5.06	4.87	5.56	4.86

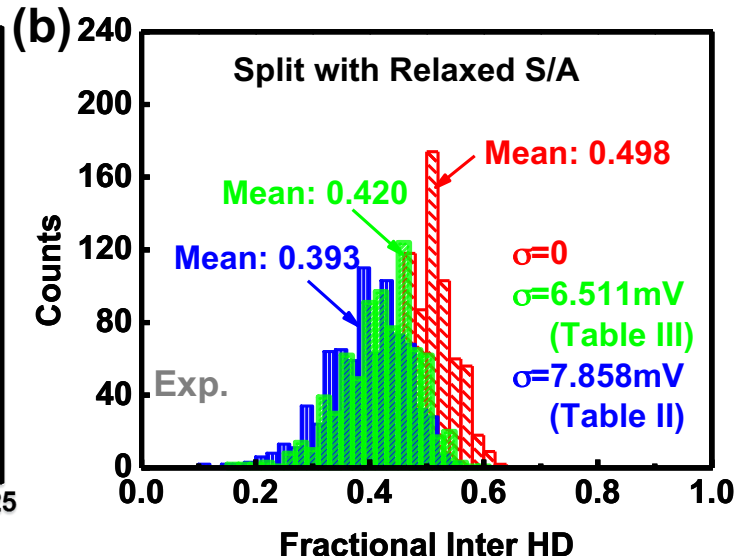
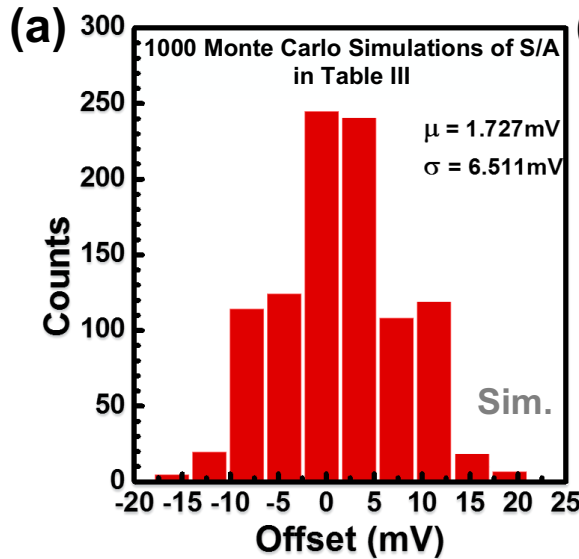
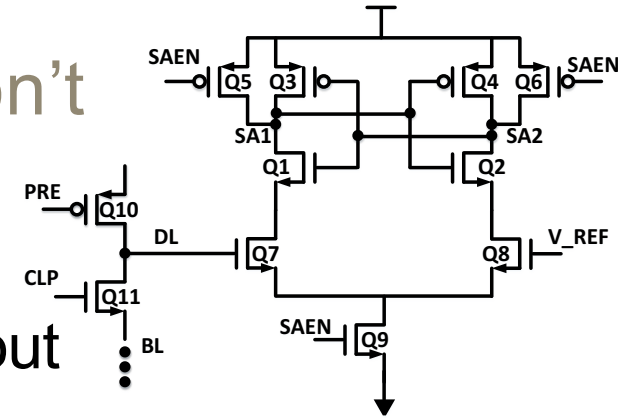
- **Dummy array is designed adjacent to the real array on-chip (resulting in larger area overhead on chip)**
- **Dummy array off-chip calibrated with the same batch fabricated with the real array (no area overhead on chip)**



# Strategies to Improve Uniqueness Con't

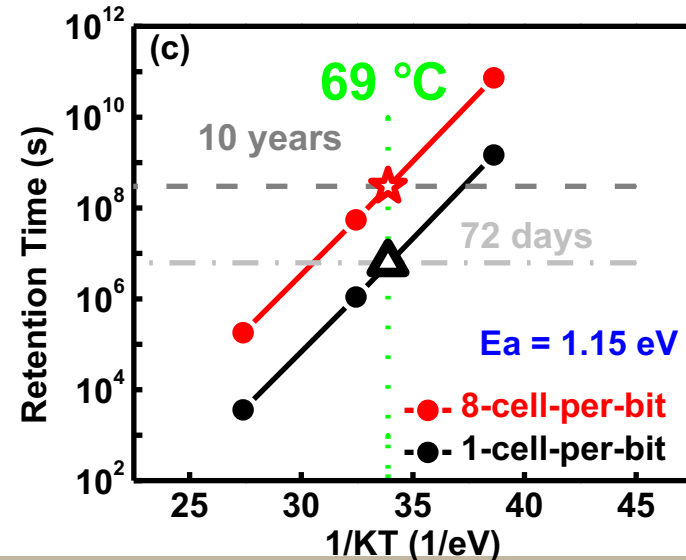
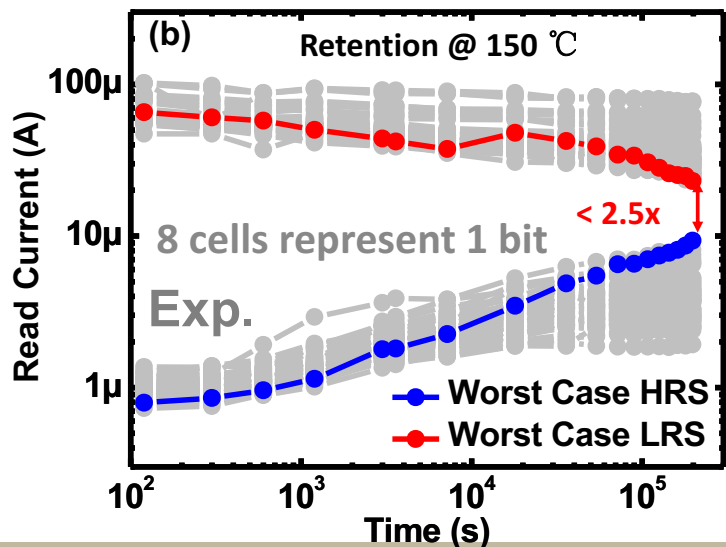
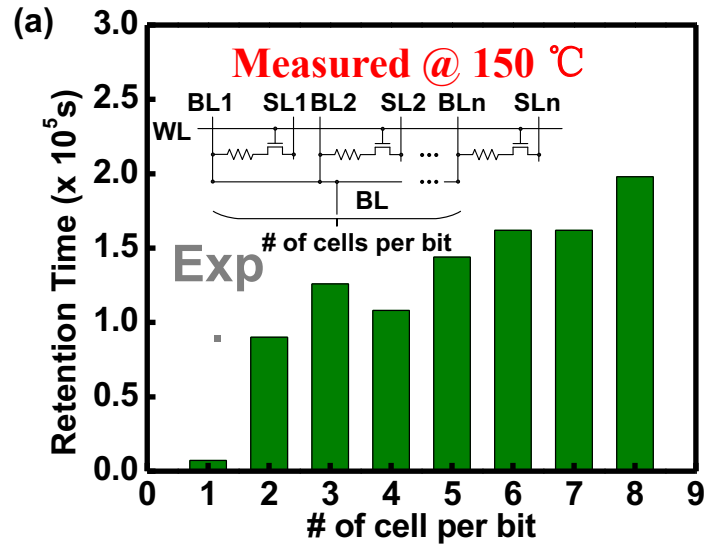
## ■ Minimizing Split S/A Offset

- 1) Symmetrical and common centroid layout design
- 2) Increasing the size the critical transistors, especially the differential input pair



# Multi-Cell-Per-Bit to Improve Reliability

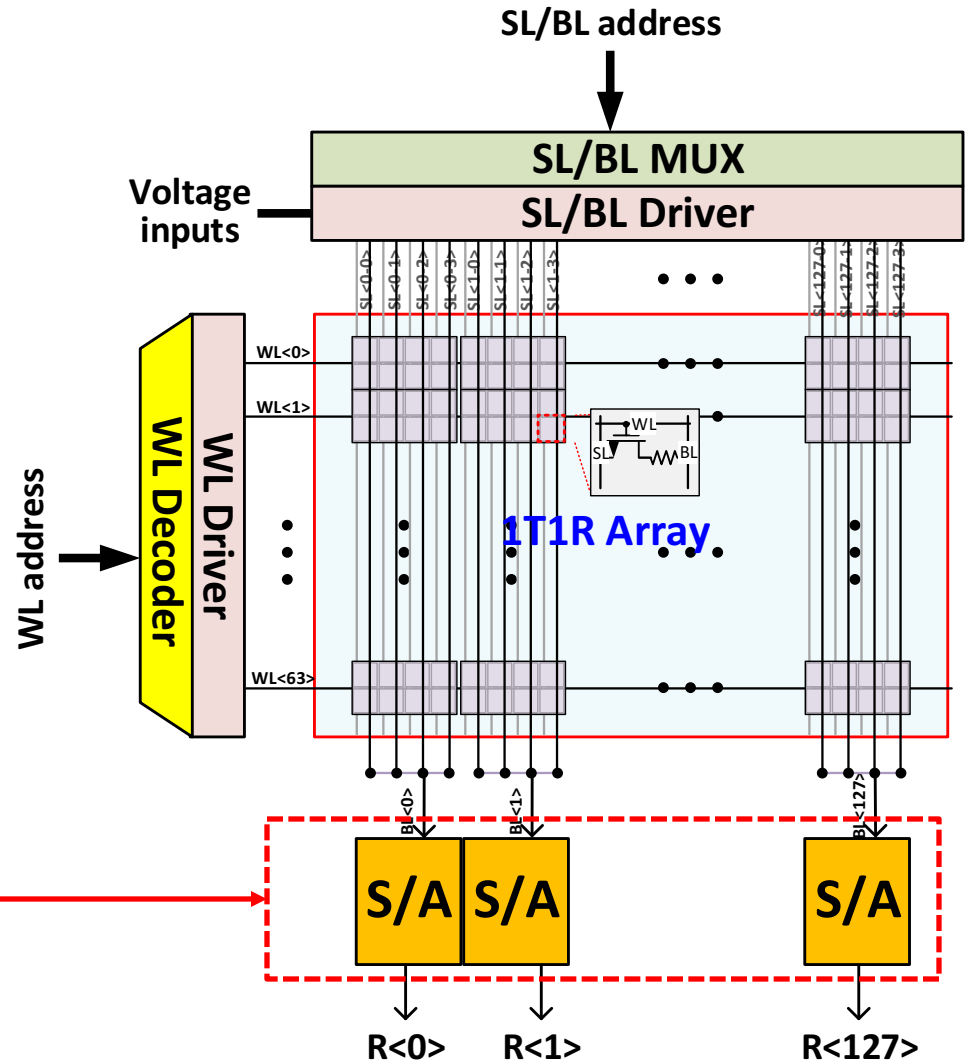
- Redundancy cells are employed to minimize the probability of early lifetime failure due to cell to cell variation.



# Layout Obfuscation for Tamper Resistance

- **Potential security issue**

An adversary might be able to microprobe the S/A



# Layout Obfuscation for Tamper Resistance

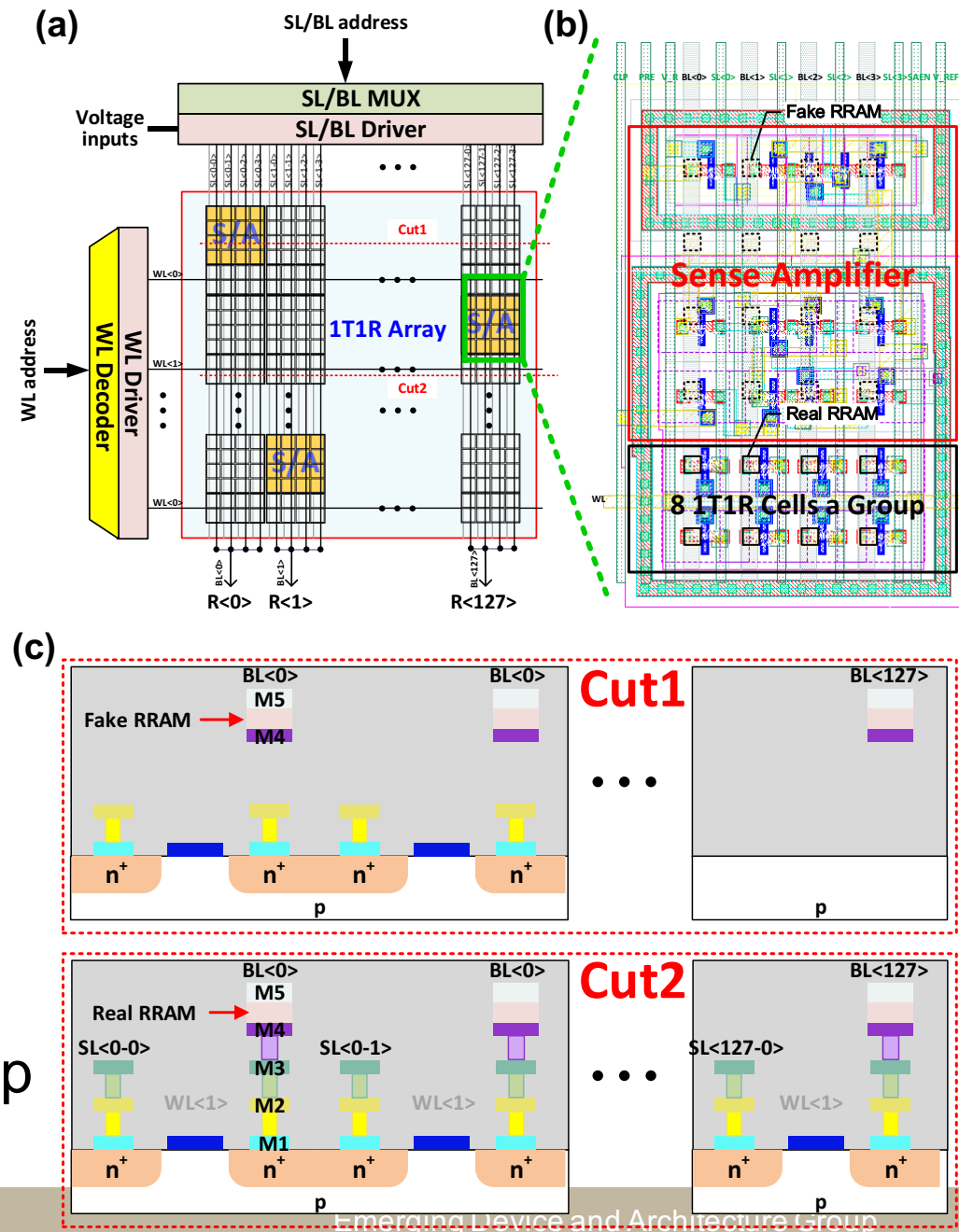
- **Potential security issue**

An adversary might be able to microprobe the S/A

- **Layout Obfuscation**

Hide S/A within 1T1R array and randomize the locations

Fake and real RRAM cells uniformly fabricated on the top



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# Area Cost and Performance Overhead Analysis Using Cadence and HSPICE

- **Array size: 64x128(1024)**
- **Circuit technology node: TSMC 65 nm**

Architecture	S/A hiding (w/ or w/o)	Latency (ns)	Energy (pJ)	Area (mm <sup>2</sup> ) *
1-cell-per-bit	w/o	4.24	9.59	0.0083
8-cell-per-bit	w/o	6.46	14.87	0.0390
	w/	16.45	17.69	0.2036

\*Including the peripheral circuits (e.g. row decoder, COL MUX, write driver and S/A)

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# Conclusion

- **Large variability of RRAM resistance in HRS was leveraged as a source of entropy for weak PUF application**
- **The performance and reliability of RRAM weak PUF were evaluated experimentally on the 1kb 1T1R arrays**
- **The factors that affect the RRAM weak PUF metrics were discussed and strategies were proposed to improve the performance and reliability**
- **The potential security problem was discussed and layout obfuscation was proposed for tamper resistance**



# Backup

# S/A sizing

## S/A TRANSISTORS' SIZE TO REDUCE OFFSET $\sigma$ TO 7.858 MV

Transistor	Q1/Q2	Q3/Q4	Q5/Q6	Q7/Q8	Q9	Q10/Q11
Gate Length (nm)	60	60	60	180	60	60
Width (nm)	240	240	120	900	120	120

## S/A TRANSISTORS' SIZE TO REDUCE OFFSET $\sigma$ TO 6.511 MV

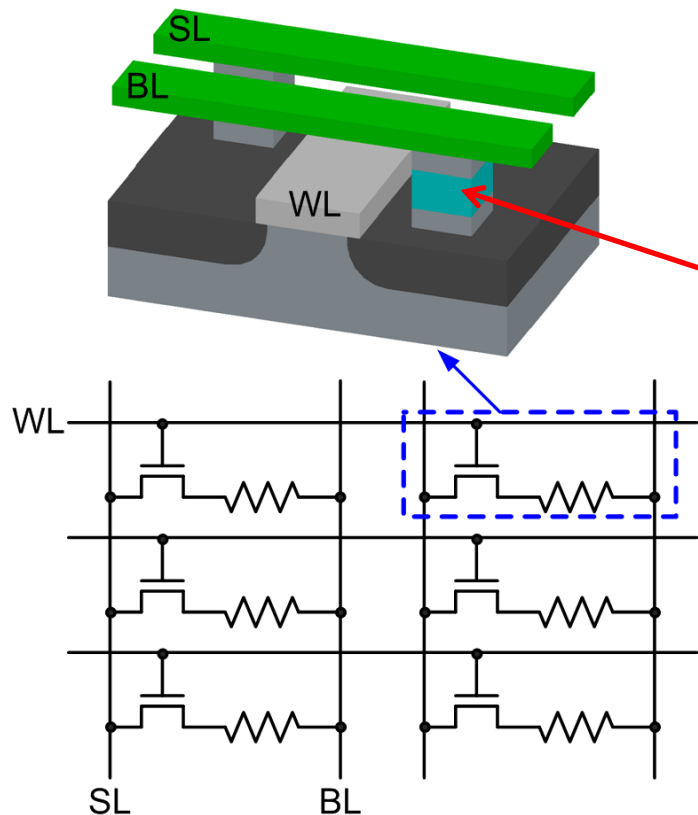
Transistor	Q1/Q2	Q3/Q4	Q5/Q6	Q7/Q8	Q9	Q10/Q11
Gate Length (nm)	60	60	60	180	60	60
Width (nm)	240	240	120	1800	240	120

# Brief Comparison of Silicon PUFs

PUF	Pros	Cons	Vulnerability
Delay based	<ul style="list-style-type: none"> <li>• Large # of CRPs</li> <li>• Mature technology</li> </ul>	Efforts for Place and Route	Machine learning attack
SRAM	Mature technology	Small # of CRPs	Photon emission attack
STT-RAM	<ul style="list-style-type: none"> <li>• Compact</li> <li>• Low fabrication cost</li> </ul>	<ul style="list-style-type: none"> <li>• ~2x ON/OFF ratio</li> <li>• Small variation in resistance</li> </ul>	Invasive probing attack (possible but very hard)
PCRAM		Retention problem (aging effect) Severity: PCRAM>RRAM	
RRAM			

# RRAM Array: 1-transistor-1-resistor (1T1R) vs. Cross-point Architecture

## 1T1R architecture



## Crossbar architecture

